

SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company

1SV263

Silicon Epitaxial Type Pin Diode for VHF, UHF, AGC Applications

Features

- Ultlasmall-sized package facilitates high-density mounting and permits 1SV263-applied equipment to be made smaller
- Small interterminal capacitance (C=0.23pF typ)
- Small forward series resistance ($r_s=2.5\Omega$ typ)

Specifications

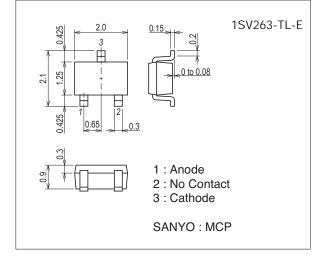
Absolute Maximum Ratings at Ta=25°C

| Parameter | Symbol | Conditions | Ratings | Unit |
|-----------------------------|--------|------------|-------------|------|
| Reverse Voltage | VR | | 50 | V |
| Forward Current | IF | | 50 | mA |
| Allowable Power Dissipation | Р | | 100 | mW |
| Junction Temperature | Tj | | 125 | °C |
| Storage Temperature | Tstg | | -55 to +125 | °C |

Package Dimensions

unit : mm (typ)





Product & Package Information

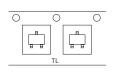
- Package
- JEITA, JEDEC : SC-70, SOT-323

: MCP

• Minimum Packing Quantity : 3,000 pcs./reel

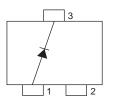
Packing Type: TL

Marking





Electrical Connection



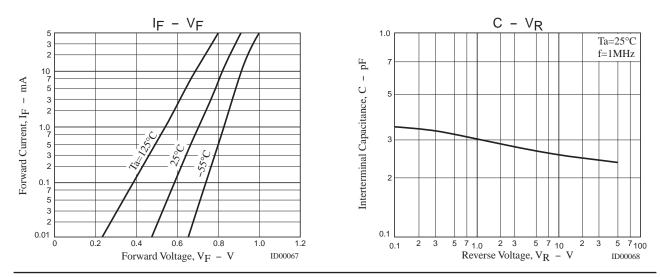
SANYO Semiconductor Co., Ltd. http://semicon.sanyo.com/en/network

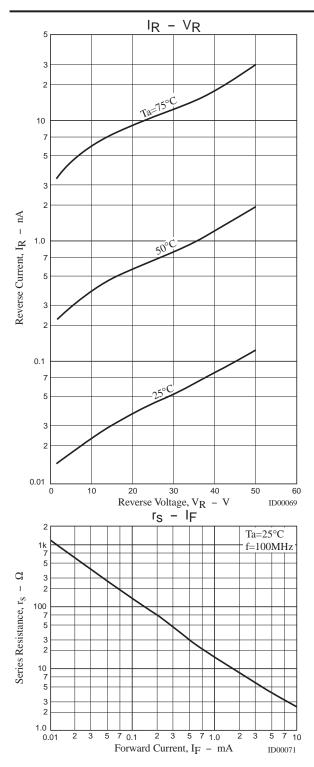
Electrical Characteristics at Ta=25°C

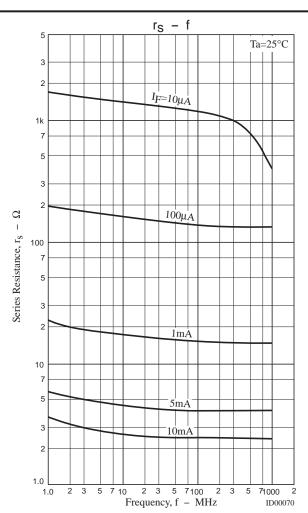
| Parameter | Symbol | Conditions | | Unit | | | |
|---------------------------|----------------|-----------------------------|-----|------|------|------|--|
| Falanietei | Symbol | Conditions | min | typ | max | Unit | |
| Reverse Voltage | VR | I _R =10μA | 50 | | | V | |
| Reverse Current | IR | V _R =50V | | | 0.1 | μΑ | |
| Forward Voltage | VF | IF=50mA | | 0.91 | 0.95 | V | |
| Interterminal Capacitance | С | V _R =50V, f=1MHz | | 0.23 | 0.4 | рF | |
| Series Resistance | r _S | IF=5mA, f=100MHz | | 4.0 | 8.0 | Ω | |
| | | IF=10mA, f=100MHz | | 2.5 | 4.5 | Ω | |

Ordering Information

| Device | Package | Shipping | memo | | |
|----------------|---------|----------------|---------|--|--|
| SV263-TL-E MCP | | 3,000pcs./reel | Pb Free | | |







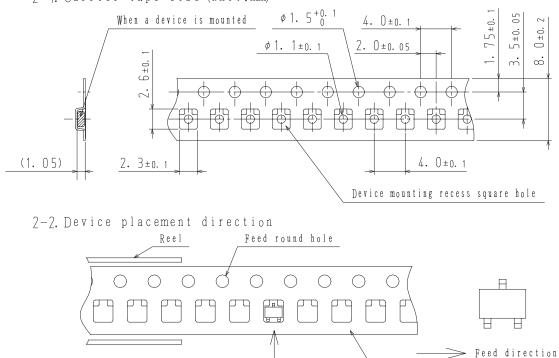
Embossed Taping Specification 1SV263-TL-E

1. Packing Format

| | | 11 | 37 1 | | | | | |
|--------------------|--------------|--|---|-----------|----------------|--|------------|---|
| Package Name | Carrier Tape | Maximum Number of devices contained (pcs) | | | Packing format | | | |
| | Туре | Reel | Inner box | Outer box | In | ner BOX | (C-1) | Outer BOX (A-7) |
| MCP | MCP | 3,000 | 15,000 | 90,000 | 5 ree | els contain | e d | 6 inner boxes contained |
| | | | | | Dime | nsions:mm (| (external) | Dimensions:mm (external) |
| | | | | | 18 | 3×72× | :185 | 440×195×210 |
| | | | Reel | label, I | [nner | box label | Outer | box label |
| <u>Packing met</u> | h o d | | | (u : | nit:r | nm) | The for | label at the time of factory shipments m of a label may change in physical ution process. |
| 0 | ~ | | L | ŧ | 69 | | L | 108 |
| | Orig | No tity - in - | -> (17 -> (0) (2) -> (AS NOTE | | | IIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIII | | TYPE CODE IIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIII |
| | Reel la | bel | | | | descriptio: terminal | | at the surface ee. |
| | | | | Label | 1 | JEITA | Phase | |
| | | | | LEAD FRI | EE 3 | JEITA F | hase 3A | |
| | | | | LEAD FRI | EE 4 | JEITA H | hase 3 | |

2. Taping configuration

2-1. Carrier tape size (unit:mm)

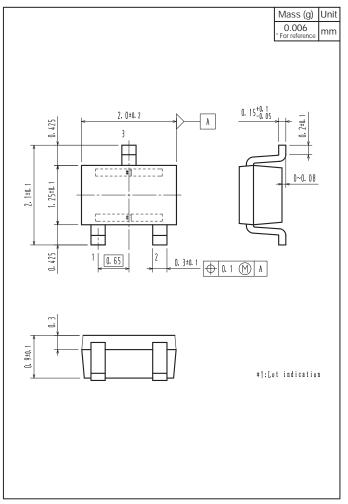


Those with oen electrode terminal on the feed hole side $\cdots TL$

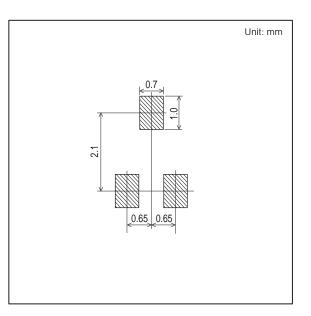
ΤL

Carrier tape

Outline Drawing 1SV263-TL-E



Land Pattern Example



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